HS/IS Radiation Hardened Types

H S 1 - 6664 RH -8

PREFIX
H: Harris
I: Intersil

FAMILY
Rad Hard/High-Rel Products

PACKAGE DESIGNATOR
1: Ceramic Dual-In-Line Frit-Seal (CERDIP) or Ceramic Dual-In-Line Metal-Seal (SBDIP)
2: Can
4: Ceramic Leadless Chip Carriers (CLCC)
7B: 8 Lead Ceramic Dual-In-Line Side-Brazed (SBDIP)
8: Ceramic Pin Grid Array (CPGA)
9: Ceramic Flatpack
0: Die
YE: SMD 0.5
9S: TO-257 Hermetic Surface Mount

PART NUMBER

HARDNESS
RH: Radiation Hardened (Note 3)
EH: Radiation Hardened (Note 3)

CLASS
-8: -55°C to +125°C QML SMD Class Q (Note 1)
-Q: -55°C to +125°C QML SMD Class V (Note 1)
-T: -55°C to +125°C QML SMD Class T (Note 1)
/PROTO: -55°C to +125°C Temperature Tested (Note 2)

NOTES:

1. FLIGHT UNITS MUST BE ORDERED BY SMD#.
   A cross reference table is available on the Intersil website at http://www.intersil.com/
2. /PROTO available for design-in/breadboarding - NOT FOR FLIGHT.
3. Refer to specific device type SMD for radiation hardness level.

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